



DFLU1200

Features and Benefits

Glass Passivated Die Construction

- Super-Fast Recovery Time for High Efficiency
- ±2kV ESD Protection (IEC61000-4-2, Contact Discharge)
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

1.0A SURFACE MOUNT SUPER-FAST RECTIFIER PowerDI123

Mechanical Data

- Case: PowerDl[®]123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.01 grams (Approximate)



Top View

Ordering Information (Note 4)

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Device	Packaging	Shipping
DFLU1200-7	PowerDI123	3000/Tape & Reel

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

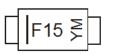
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http:// www.diodes.com/products/packages.html.

Marking Information

Notes:



F15 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: E = 2017) M = Month (ex: 9 = September)

Date Code K	еу												
Year	2005			2013	2014	2015	2016	2017	2018	2019	2020	2021	2022
Code	S			А	В	С	D	Е	F	G	Н	I	J
Month		lan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1	2	3	4	5	6	7	8	9	0	Ν	D

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Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.			
Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
RMS Reverse Voltage	V _{R(RMS)}	140	V
Average Rectified Output Current (See Figure 4)	lo	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	A

Thermal Characteristics

Characteristic		Symbol	Тур	Max	Unit
Power Dissipation (Note 6)	@ T _A = +25°C	PD	—	1.0	W
Thermal Resistance Junction to Soldering Point (Note 7)		$R_{\theta JS}$	—	6	°C/W
Thermal Resistance Junction to Ambient (Note 6)	@T _A = +25°C	$R_{\theta JA}$	116	—	°C/W
Thermal Resistance Junction to Ambient (Note 8)	@T _A = +25°C	$R_{\theta JA}$	182	—	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-65 to	o +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Minimum Reverse Breakdown Voltage	@I _R = 5μΑ	V _(BR)	200	V
Maximum Forward Voltage Drop	@ I _F = 0.6A @ I _F = 1.0A	V_{FM}	0.90 0.98	V
Peak Reverse Current at Rated DC Blocking Voltage (Note 5)	@ T _A = +25°C @ T _A = +100°C	I _{RM}	5.0 200	μΑ
Reverse Recovery Time (Note 9)		t _{RR}	25	ns
Typical Total Capacitance (f = 1MHz, V _R = 4VI	DC)	CT	27	pF

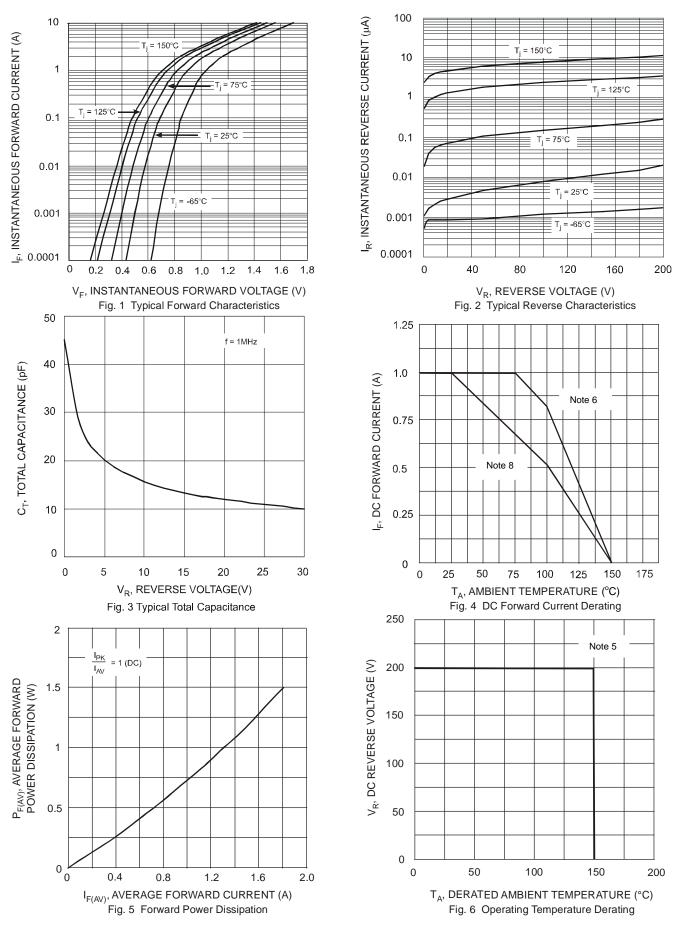
Notes: 5. Short duration pulse test used to minimize self-heating effect.

6. Device mounted on 1" x 1", Polymide PCB; 2 oz. Cu pad layout as shown on Diodes Incorporated's website http://www.diodes.com/package-outlines.html.

Theoretical R_{aus} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
Device mounted on FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.

9. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$. See figure 7.







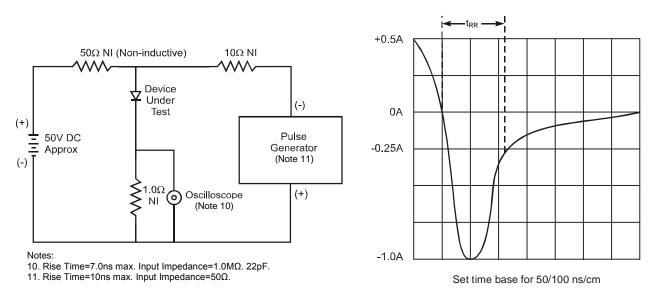
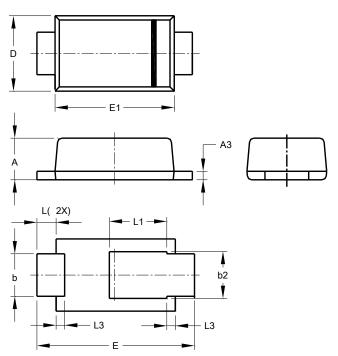


Fig. 7 Reverse Recovery Time Characteristic and Test Circuit



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

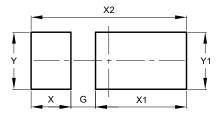


PowerDI123						
Dim	Min	Max	Тур			
Α	0.93	1.00	0.98			
A3	0.15	0.25	0.20			
b	0.85	1.25	1.00			
b2	1.025	1.125	1.10			
D	1.63	1.93	1.78			
E	3.50	3.90	3.70			
E1	2.60	3.00	2.80			
L	0.40	0.50	0.45			
L1	1.25	1.40	1.35			
L3	0.125	0.275	0.20			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI123



Dimensions	Value (in mm)		
G	0.65		
Х	1.05		
X1	2.40		
X2	4.10		
Y	1.50		
Y1	1.50		



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